

4-channel I²C-bus switch with reset

Datasheet (EN) 1.3

Product Overview

The NCA9546 is a quad bidirectional translating switch controlled via the I²C bus. The SCL/SDA upstream pair fans out to four downstream pairs, or channels. Any individual SCn/SDn channel or combination of channels can be selected, determined by the contents of the programmable control register.

An active-low reset (/RESET) input allows the NCA9546 to recover from a situation in which one of the downstream I²C buses is stuck in a low state. Pulling /RESET low resets, the I²C state machine and causes all the channels to be deselected, as does the internal power-on reset function.

The pass gates of the switches are constructed such that the VCC terminal can be used to limit the maximum high voltage, which will be passed by the NCA9546. This allows the use of different bus voltages on each pair, so that 1.8-V, 2.5-V, or 3.3-V parts can communicate with 5-V parts, without any additional protection. External pullup resistors pull the bus up to the desired voltage level for each channel. All I/O terminals are 5.5 V tolerant.

Key Features

- 1-of-4 Bidirectional Translating Switches
- I²C Bus and SMBus Compatible
- Active-Low Reset Input
- Three Address Terminals, Allowing up to Eight Devices on the I²C Bus
- Channel Selection via I²C Bus, in Any Combination
- Power-Up with All Switch Channels Deselected
- Low Ron Switches
- Allows Voltage-Level Translation Between 1.8-V, 2.5-V, 3.3-V, and 5-V Buses
- No Glitch on Power-Up
- Supports Hot Insertion
- Low Standby Current
- Operating Power-Supply Voltage Range of 1.7 V to 5.5 V

- 5.5 V Tolerant Inputs
- 0 to 400-kHz Clock Frequency
- Latch-Up Performance Exceeds 100 mA per JESD 78
- RoHS & REACH compliant
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

Applications

- Servers
- Routers (Telecom Switching Equipment)
- Factory Automation
- Products with I²C Slave Address Conflicts (e.g. Multiple, Identical Temp Sensors)

Device Information

Part Number	Package	Body Size
NCA9546-DTSPR	TSSOP16	5.0mm*4.4mm
NCA9546-DQNPR	QFN16	4.0mm*4.0mm
NCA9546-DSPNR	SOP16	9.9mm*3.9mm

Pin Configuration

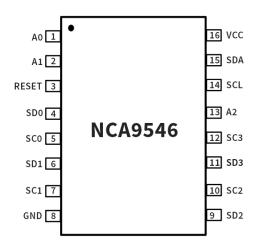


Figure 1. NCA9546 pin configuration

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1. Pin Configuration and Functions

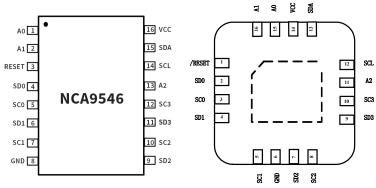


Figure 1.1 NCA9546 Package

Table 1.1 Pin Configuration and Description

Symbol	TSSOP16 Pin	SOP16 PIN	QFN16	Description
A0	1	1	15	Address input 0. Connect directly to VCC or ground.
A1	2	2	16	Address input 1. Connect directly to VCC or ground.
/RESET	3	3	1	Active-low reset input. Connect to VCC or VDPUM¹ through a pull-up resistor if not used.
SD0	4	4	2	Serial data 0. Connect to V _{DPU0} ¹ through a pul-up resistor.
SC0	5	5	3	Serial clock 0. Connect to V _{DPUO} ¹ through a pull-up resistor.
SD1	6	6	4	Serial data 1. Connect to V _{DPU1} ¹ through a pull-up resistor.
SC1	7	7	5	Serial clock 1. Connect to V _{DPU1} ¹ through a pull-up resistor.
GND	8	8	6	Ground
SD2	9	9	7	Serial data 2. Connect to V _{DPU2} 1 through a pull-up resistor.
SC2	10	10	8	Serial clock 2. Connect to V _{DPU2} 1 through a pull-up resistor.
SD3	11	11	9	Serial data 3. Connect to V _{DPU3} ¹ through a pull-up resistor.
SC3	12	12	10	Serial clock 3. Connect to V _{DPU3} 1 through a pull-up resistor.
A2	13	13	11	Address input 2. Connect directly to VCC or ground.
SCL	14	14	12	Serial clock line. Connect to V _{DPUM} ¹ through a pull-up resistor.
SDA	15	15	13	Serial data line. Connect to V _{DPUM} ¹ through a pull-up resistor.
VCC	16	16	14	Supply power

 $^{^{1}}$ V_{DPUX} is the pull-up reference voltage for the associated data line. V_{DPUM} is the master I²C master reference voltage and V_{DPU0}–V_{DPU3} are the slave channel reference voltages.

2. Absolute Maximum Ratings

Parameters	Symbol	Min	Мах	Unit	Conditions
Supply Voltage	V_{cc}	-0.5	7	٧	
Input/output Voltage	V_{I}/V_{O}	-0.5	7	٧	
Input current	I _I		±25	mA	
Output current	Ιο		±25	mA	Vo<0V
Continuous current through VCC or GND	I _{cc}		±100	mA	
Storage Temperature	Tstg	-65	150	°C	

3. ESD rating

	Ratings	Value	Unit
	Human body model (HBM), per AEC-Q100-002-RevD		
Flootrostatic discharge	All pins	±2.0	kV
Electrostatic discharge	Charged device model (CDM), per AEC-Q100-011-RevB		
	All pins	±1000	V

4. Recommended Operating Conditions

Parameters	Symbol	Min	Max	Unit	Conditions
Supply voltage	Vcc	1.7	5.5	V	
		0.7*Vcc	6	V	SCL, SDA
High-level input voltage	V_{IH}	0.7*Vcc	V _{cc} +0.5	V	A2, A1, A0, INT3-INT0,
					RESET
		-0.5	0.3*Vcc	V	SCL, SDA
Low-level input voltage	V_{IL}	-0.5	0.3*Vcc	V	A2, A1, A0, INT3-INT0,
					RESET
Operating free-air temperature	T _A	-40	105	°C	

5. Thermal Information

Parameters	Symbol	TSSOP16	QFN16	SOP16	Unit
Junction-to-ambient thermal resistance	θја	115.3	40.6	158.7	°C/W
Junction-to-case(top) thermal resistance	θ _{JC} (top)	48.7	39.5	52.3	°C/W
Junction-to-board thermal resistance	Ө ЈВ	66.4	39.2	53.6	°C/W

6. Specifications

6.1. Electrical Characteristics

 $V_{CC} = 1.7V$ to 5.5V; $T_{amb} = -40$ °C to +105°C; unless otherwise noted. Typical specification are at $T_A = 25$ °C, $V_{CC} = 3.3V$

Parameters	Symb	Min	Тур	Max	Unit	Conditions
	ol					
Supply						
Supply voltage Range	V_{cc}	1.7	-	5.5	V	
Power On Reset rising	V_{PORR}	-	1.15	1.4	V	no load; V _I = V _{CC} or GND
Power On Reset falling	V _{PORF}	0.9	1.08		V	no load; VI = V _{cc} or GND
Supply current	Icc	-	-	10	μΑ	Operating mode; $V_{CC} = 5.5 \text{ V}$; $V_I = V_{CC}$ or GND; no load; $f_{SCL} = 100 \text{ kHz}$
Standby current	I _{stb}	-	0.3	5	μΑ	Standby mode; V _{cc} = 5.5 V; V _i =V _{cc} or GND; no load
Input SCL; Input/Outpu	it SDA					
LOW-level input	V_{IL}	-0.5	-	0.3*V _{cc}	V	
voltage	- 12			112 100		
HIGH-level input voltage	V _{IH}	0.7*V _{CC}	-	6	V	When V _{cc} =1.7V-2.3V, the minimum value of VIH is 0.8*V _{cc}
LOW-level output	I _{OL}	2.5	15	-	mA	V _{OL} =0.4V
current		4	20		mA	V _{OL} =0.6V
Input leakage current	IL	-1	-	+1	μΑ	$V_1 = V_{CC}$ or GND
Input capacitance	Ci	_	15		pF	V _I = GND
піриї сараспапсе	Ci	_	13		PF	VI – GIND
Select inputs A0,A1,A2,	RESET					
LOW-level input	V_{IL}	-0.5	-	0.3*V _{cc}	V	
voltage						
HIGH-level input	V _{IH}	0.7*V _{cc}	-	6	V	When V _{cc} =1.7V-2.3V, the minimum
voltage		777 7 66				value of VIH is 0.8*V _{cc}
voltage Leakage current	IL	-1	-	1	μА	
	I _L		- 1.6	1 3	μA pF	value of VIH is 0.8*Vcc
Leakage current		-1			+ -	value of VIH is $0.8*V_{CC}$ $V_1 = V_{CC}$ or GND
Leakage current Input capacitance		-1 -			+ -	value of VIH is $0.8*V_{cc}$ $V_1 = V_{cc} \text{ or GND}$ $V_1 = \text{GND}$ $V_0 = 0.4 \text{ V}, I_0 = 15 \text{ mA}, V_{cc} = 4.5 \text{ V}$
Leakage current Input capacitance Pass gate	Ci	-1 - 4 5	1.6 14 16	3	pF	value of VIH is $0.8*V_{CC}$ $V_{I} = V_{CC} \text{ or GND}$ $V_{I} = GND$
Leakage current Input capacitance Pass gate	Ci	-1 -	1.6 14 16 19	3 20	+ -	value of VIH is $0.8*V_{cc}$ $V_1 = V_{cc} \text{ or GND}$ $V_1 = \text{GND}$ $V_0 = 0.4 \text{ V}, I_0 = 15 \text{ mA}, V_{cc} = 4.5 \text{ V}$
Leakage current Input capacitance Pass gate	Ci	-1 - 4 5	1.6 14 16	3 20 25	pF	$value \ of \ VIH \ is \ 0.8^{*}V_{cc}$ $V_{I} = V_{cc} \ or \ GND$ $V_{I} = GND$ $Vo=0.4 \ V, \ I_{0} = 15 \ mA, \ V_{cc} = 4.5V$ $Vo=0.4 \ V, \ I_{0} = 15 \ mA, \ V_{cc} = 3V$
Leakage current Input capacitance Pass gate	Ci	-1 - 4 5 6	1.6 14 16 19	3 20 25 30	pF	$value \ of \ VIH \ is \ 0.8^{*}V_{cc}$ $V_{i} = V_{cc} \ or \ GND$ $V_{i} = GND$ $Vo=0.4 \ V, \ I_{o} = 15 \ mA, \ V_{cc} = 4.5V$ $Vo=0.4 \ V, \ I_{o} = 15 \ mA, \ V_{cc} = 3V$ $Vo=0.4 \ V, \ I_{o} = 10 \ mA, \ V_{cc} = 2.3V$
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6	1.6 14 16 19 28	3 20 25 30	pF	$value \ of \ VIH \ is \ 0.8^{*}V_{cc}$ $V_{i} = V_{cc} \ or \ GND$ $V_{i} = GND$ $Vo=0.4 \ V, \ I_{o} = 15 \ mA, \ V_{cc} = 4.5V$ $Vo=0.4 \ V, \ I_{o} = 15 \ mA, \ V_{cc} = 3V$ $Vo=0.4 \ V, \ I_{o} = 10 \ mA, \ V_{cc} = 2.3V$ $Vo=0.4 \ V, \ I_{o} = 10 \ mA, \ V_{cc} = 1.7V$
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10	1.6 14 16 19 28	3 20 25 30 40	pF	$value \ of \ VIH \ is \ 0.8^{*}V_{CC}$ $V_{I} = V_{CC} \ or \ GND$ $V_{I} = GND$ $Vo=0.4 \ V, \ I_{O} = 15 \ mA, \ V_{CC} = 4.5V$ $Vo=0.4 \ V, \ I_{O} = 15 \ mA, \ V_{CC} = 3V$ $Vo=0.4 \ V, \ I_{O} = 10 \ mA, \ V_{CC} = 2.3V$ $Vo=0.4 \ V, \ I_{O} = 10 \ mA, \ V_{CC} = 1.7V$ $V_{CC} = 5 \ V, \ I_{O(SW)} = -100 \ \mu A$ $V_{CC} = 4.5V \ to 5.5 \ V, \ I_{O(SW)} = -100 \ \mu A$
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10	1.6 14 16 19 28 3.64	3 20 25 30 40 4.5	pF	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5V$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7V$ V _{CC} = 5 V, $I_{O(SW)} = -100\mu$ A V _{CC} = 4.5V to 5.5 V, $I_{O(SW)} = -100\mu$ A V _{CC} = 3.3 V, $I_{O(SW)} = -100\mu$ A
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10	1.6 14 16 19 28 3.64	3 20 25 30 40	pF	value of VIH is 0.8^*V_{CC} $V_1 = V_{CC}$ or GND $V_1 = GND$ Vo=0.4 V, $I_0 = 15$ mA, $V_{CC} = 4.5V$ Vo=0.4 V, $I_0 = 15$ mA, $V_{CC} = 3V$ Vo=0.4 V, $I_0 = 10$ mA, $V_{CC} = 2.3V$ Vo=0.4 V, $I_0 = 10$ mA, $V_{CC} = 1.7V$ V _{CC} = 5 V, $I_{O(SW)} = -100\mu$ A V _{CC} = 4.5V to 5.5 V, $I_{O(SW)} = -100\mu$ A V _{CC} = 3.3 V, $I_{O(SW)} = -100\mu$ A V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100\mu$ A
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10	1.6 14 16 19 28 3.64	3 20 25 30 40 4.5	pF	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5$ V Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7$ V V _{CC} = 5 V, $I_{O(SW)} = -100$ μA V _{CC} = 4.5V to 5.5 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 2.5 V, $I_{O(SW)} = -100$ μA
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10 2.6	1.6 14 16 19 28 3.64 2.15	3 20 25 30 40 4.5	pF	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5V$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7V$ Vcc = 5 V, $I_{O(SW)} = -100\mu$ A Vcc = 4.5V to 5.5 V, $I_{O(SW)} = -100\mu$ A Vcc = 3.3 V, $I_{O(SW)} = -100\mu$ A Vcc = 3 V to 3.6 V, $I_{O(SW)} = -100\mu$ A Vcc = 2.5 V, $I_{O(SW)} = -100\mu$ A Vcc = 2.3 V to 2.7 V, $I_{O(SW)} = -100\mu$ A
Leakage current Input capacitance Pass gate On-state resistance	C _i	-1 - 4 5 6 10 2.6	1.6 14 16 19 28 3.64	3 20 25 30 40 4.5 2.8	pF	value of VIH is $0.8^{+}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5V$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3V$ Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7V$ Vcc = 5 V, $I_{O(SW)} = -100\mu$ A Vcc = 4.5V to 5.5 V, $I_{O(SW)} = -100\mu$ A Vcc = 3.3 V, $I_{O(SW)} = -100\mu$ A Vcc = 3 V to 3.6 V, $I_{O(SW)} = -100\mu$ A Vcc = 2.5 V, $I_{O(SW)} = -100\mu$ A Vcc = 2.3 V to 2.7 V, $I_{O(SW)} = -100\mu$ A Vcc = 1.8 V, $I_{O(SW)} = -100\mu$ A
Leakage current Input capacitance Pass gate On-state resistance Switch output voltage	C _i R _{on}	-1 - 4 5 6 10 2.6 1.6	1.6 14 16 19 28 3.64 2.15 1.46	3 20 25 30 40 4.5 2.8 1.9	pF Ω	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5$ V Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7$ V V _{CC} = 5 V, $I_{O(SW)} = -100$ μA V _{CC} = 4.5V to 5.5 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 2.5 V, $I_{O(SW)} = -100$ μA V _{CC} = 2.3 V to 2.7 V, $I_{O(SW)} = -100$ μA V _{CC} = 1.8 V, $I_{O(SW)} = -100$ μA V _{CC} = 1.7 V to 1.95 V, $I_{O(SW)} = -100$ μA
Leakage current Input capacitance Pass gate On-state resistance Switch output voltage Leakage current	C _i R _{on}	-1 - 4 5 6 10 2.6 1.6 1	1.6 14 16 19 28 3.64 2.15 1.46	3 20 25 30 40 4.5 2.8 1.9	pF Ω V	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5$ V Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7$ V Vc=0.4 V, $I_{O} = 10$ mA, $I_{CC} = 1.7$ V Vc=5 V, $I_{O(SW)} = -100$ μA Vc=3.3 V, $I_{O(SW)} = -100$ μA Vc=3.3 V, $I_{O(SW)} = -100$ μA Vc=3 V to 3.6 V, $I_{O(SW)} = -100$ μA Vc=2.5 V, $I_{O(SW)} = -100$ μA Vc=2.3 V to 2.7 V, $I_{O(SW)} = -100$ μA Vc=1.8 V, $I_{O(SW)} = -100$ μA Vc=1.7 V to 1.95 V, $I_{O(SW)} = -100$ μA Vc=1.7 V to 1.95 V, $I_{O(SW)} = -100$ μA
Leakage current Input capacitance Pass gate On-state resistance Switch output voltage	C _i R _{on}	-1 - 4 5 6 10 2.6 1.6	1.6 14 16 19 28 3.64 2.15 1.46	3 20 25 30 40 4.5 2.8 1.9	pF Ω	value of VIH is $0.8^{*}V_{CC}$ $V_{I} = V_{CC}$ or GND $V_{I} = GND$ Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 4.5$ V Vo=0.4 V, $I_{O} = 15$ mA, $V_{CC} = 3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 2.3$ V Vo=0.4 V, $I_{O} = 10$ mA, $V_{CC} = 1.7$ V V _{CC} = 5 V, $I_{O(SW)} = -100$ μA V _{CC} = 4.5V to 5.5 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 3 V to 3.6 V, $I_{O(SW)} = -100$ μA V _{CC} = 2.5 V, $I_{O(SW)} = -100$ μA V _{CC} = 2.3 V to 2.7 V, $I_{O(SW)} = -100$ μA V _{CC} = 1.8 V, $I_{O(SW)} = -100$ μA V _{CC} = 1.7 V to 1.95 V, $I_{O(SW)} = -100$ μA

6.2. Dynamic Characteristics

Parameters	Symbol	Standard-mode I ² C-		Fast-mode I ² C-bus		Unit
		bus				
	1	Min	Мах	Min	Max	
propagation delay	t _{PD} ¹		0.3		0.3	ns
SCL clock frequency	f _{SCL}	0	100	0	400	kHz
bus free time between a STOP and START	t _{BUF}	4.7	-	1.3	-	μs
condition						
hold time (repeated) START condition	t _{HD;STA} ²	4.0	-	0.6	-	μs
set-up time for a repeated START condition	t _{SU;STA}	4.7	-	0.6	-	μs
set-up time for STOP condition	t _{su;sto}	4.0	-	0.6	-	μs
data valid acknowledge time	t _{VD;ACK}		1		1	μs
data hold time	t _{HD;DAT} 3	0	3.45	0	0.9	ns
data valid time(high to low)	t _{VD;DAT} 4		1		1	μs
data valid time(low to high)			0.6		0.6	μs
data set-up time	t _{SU;DAT}	250	-	100	-	ns
LOW period of the SCL clock	t _{LOW}	4.7	-	1.3	-	μs
HIGH period of the SCL clock	t _{HIGH}	4.0	-	0.6	-	μs
fall time of both SDA and SCL signals	t _f	-	300	20 +	300	ns
				0.1C _b ⁵		
rise time of both SDA and SCL signals	t _r	-	1000	20 +	300	ns
				0.1C _b ⁵		
pulse width of spikes that must be	t _{SP}	-	50	-	50	ns
suppressed by the input filter						
/RESET						
Low-level reset time	$T_{w(rst)L}$	4		4		ns
Reset time ⁶	t _{rst}	500		500		ns
Recovery time to START condition	t _{REC:STA}	0		0		ns

 $^{^{1}}$ Pass gate propagation delay is calculated from the 20 Ω typical Ron and the 15 pF load capacitance.

²After this period, the first clock pulse is generated.

³A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the V_{IH(min)} of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

 $^{^4}$ Measurements taken with 1 k Ω pull-up resistor and 50 pF load.

⁵C_b = total capacitance of one bus line in pF.

⁶The minimum Reset time of the ACK bit is 600ns.

6.3. Parameter Measurement Information

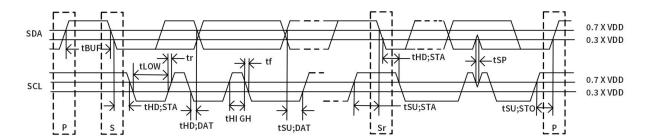


Figure 6.1 Definition of timing on I²C-bus

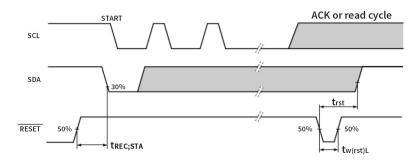


Figure 6.2 Definition of RESET timing

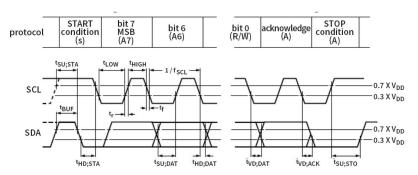
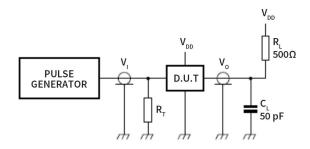


Figure 6.3 I²C-bus timing diagram



Definitions test circuit:

 R_L = Load resistance.

 C_L = Load capacitance including jig and probe capacitance.

 $R_{\text{\scriptsize T}}$ = Termination resistance should be equal to the output impedance Zo of the pulse generator.

Figure 6.4 Test circuitry for switching times

7. Detailed Description

7.1. Overview

The NCA9546 is a 4-channel, bidirectional translating I²C switch. The master SCL/SDA signal pair is directed to four channels of slave devices, SC0/SD0-SC3/SD3. Any individual downstream channel can be selected as well as any combination of the four channels. The device offers an active-low /RESET input which resets the state machine and allows the NCA9546 to recover should one of the downstream I²C buses get stuck in a low state. The state machine of the device can also be reset by cycling the power supply, Vcc, also known as a power-on reset (POR) Both the RESET function and a POR will cause all channels to be deselected.

The connections of the I²C data path are controlled by the same I²C master device that is switched to communicate with multiple I²C slaves. After the successful acknowledgment of the slave address (hardware selectable by A0, A1 and A2 terminals), a single 8-bit control register is written to or read from to determine the selected channels and state of the interrupts.

The NCA9546 may also be used for voltage translation, allowing the use of different bus voltages on each SCn/SDn pair such that 1.8-V, 2.5-V, or 3.3-V parts can communicate with 5-V parts. This is achieved by using external pull-up resistors to pull the bus up to the desired voltage for the master and each slave channel.

7.2. Functional Block Diagram

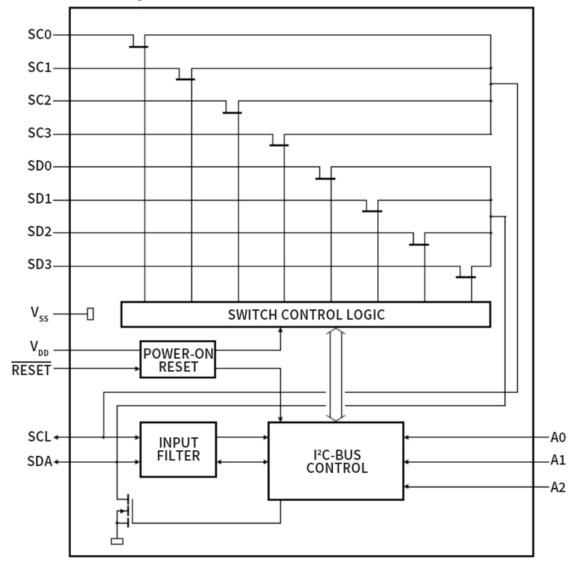


Figure 7.1 NCA9546 Functional block

7.3. Feature Description

The NCA9546 is a 4-channel, bidirectional translating switch for I²C buses that supports Standard-Mode (100 kHz) and Fast-Mode (400 kHz) operation. The NCA9546 features I²C control using a single 8-bit control register in which the four least significant bits control the enabling and disabling of the 4 switch channels of I²C data flow.

The NCA9546 also be used for voltage translation, allowing the use of 1.8-V, 2.5-V, or 3.3-V parts to communicate with 5-V parts. Additionally, in the event that communication on the I²C bus enters a fault state, the NCA9546 can be reset to resume normal operation using the /RESET pin feature or by a power-on reset which results from cycling power to the device.

7.4. Device Functional Modes

/RESET Input

The /RESET input can be used to recover the NCA9546 from a bus-fault condition. The registers and the I²C state machine within this device initialize to their default states if this signal is asserted low for a minimum of t_{WL}.

All channels also are deselected in this case. /RESET must be connected to Vcc through a pull-up resistor.

Power-On Reset

When power is applied to VCC, an internal power-on reset holds the NCA9546 in a reset condition until V_{CC} has reached V_{PORR} . At this point, the reset condition is released and the NCA9546 registers and I^2C state machine are initialized to their default states, all zeroes, causing all the channels to be deselected. Thereafter, V_{CC} must be lowered below at least V_{PORF} to reset the device.

7.5. Programming

I²C Interface

The I²C bus is for two-way two-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer can be initiated only when the bus is not busy.

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high period of the clock pulse, as changes in the data line at this time are interpreted as control signals (see Figure 7.2)

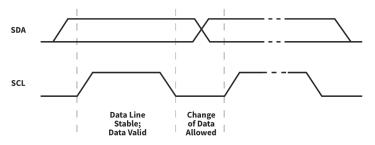


Figure 7.2 Bit Transfer

Both data and clock lines remain high when the bus is not busy. A high-to-low transition of the data line while the clock is high is defined as the start condition (S). A low-to-high transition of the data line while the clock is high is defined as the stop condition (P) (see Figure 7.3).

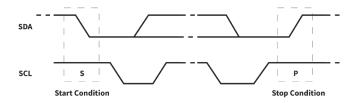


Figure 7.3 Definition of Start and Stop Conditions

A device generating a message is a transmitter; a device receiving a message is the receiver. The device that controls the message is the master, and the devices that are controlled by the master are the slaves (see Figure 7.4).

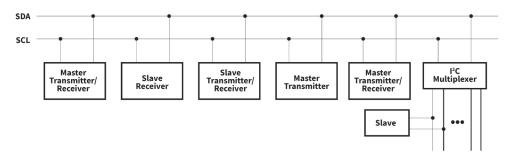


Figure 7.4 System Configuration

The number of data bytes transferred between the start and the stop conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge (ACK) bit. The transmitter must release the SDA line before the receiver can send an ACK bit.

When a slave receiver is addressed, it must generate an ACK after the reception of each byte. Also, a master must generate an ACK after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges must pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see Figure 7.5). Setup and hold times must be taken into account.

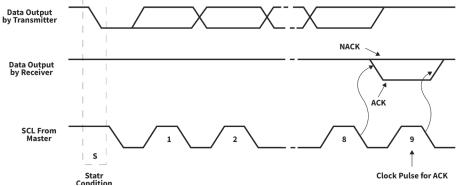


Figure 7.5 Acknowledgment on the I²C Bus

A master receiver must signal an end of data to the transmitter by not generating an acknowledge (NACK) after the last byte has been clocked out of the slave. This is done by the master receiver by holding the SDA line high. In this event, the transmitter must release the data line to enable the master to generate a stop condition. Data is transmitted to the NCA9546 control register using the write mode shown in Figure 7.6.

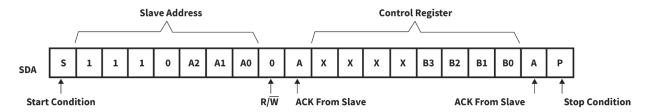


Figure 7.6 Write Control Register

Data is read from the NCA9546 control register using the read mode shown in Figure 7.7.

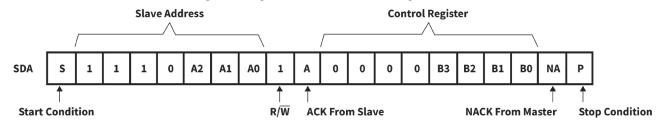


Figure 7.7 Read Control Register

7.6. Control Register

Device Address

Following a start condition, the bus master must output the address of the slave it is accessing. The address of the NCA9546 is shown in Figure 7.8. To conserve power, no internal pull-up resistors are incorporated on the hardware-selectable address terminals, and they must be pulled high or low.

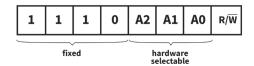


Figure 7.8 NCA9546 Address

The last bit of the slave address defines the operation to be performed. When set to a logic 1, a read is selected, while a logic 0 selects a write operation.

Control Register Description

Following the successful acknowledgment of the slave address, the bus master sends a byte to the NCA9546, which is stored in the control register (see Figure 7.9). If multiple bytes are received by the NCA9546, it saves the last byte received. This register can be written and read via the I²C bus.

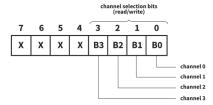


Figure 7.9 Control Register

7.7. Control Register Definition

One or several SCn/SDn downstream pairs, or channels, are selected by the contents of the control register (see Table 6.1). After the NCA9546 has been addressed, the control register is written. The four LSBs of the control byte are used to determine which channel or channels are to be selected. When a channel is selected, the channel becomes active after a stop condition has been placed on the I²C bus. This ensures that all SCn/SDn lines are in a high state when the channel is made active, so that no false conditions are generated at the time of connection. A stop condition must occur always right after the acknowledge cycle.

Table 7.1. Control Register Write ((Channel Selection)), Control Register Read	(Channel Status) ¹

В7	В6	В5	В4	ВЗ	В2	B1	ВО	COMMAND
Х	Х	Х	Х	Х	Х	Х	0	Channel 0 disable
^	Χ	Χ	Χ	Λ	Λ	Λ	1	Channel 0 enable
V	Х	Х		V	V	0	V	Channel 1 disable
X		X	Х	Х	Х	1	X	Channel 1 enable
Х	х	Х	Х	· ·	0	V	Х	Channel 2 disable
^		X		X	1	X		Channel 2 enable
V	V	.,	Х	0	V	Х	V	Channel 3 disable
X	Х	Х	Λ	1	Х	^	Х	Channel 3 enable
0	0	0	0	0	0	0	0	No channel selected, Power-up/reset default state

¹ Several channels can be enabled at the same time. For example, B3 = 0, B2 = 1, B1 = 1, B0 = 0 means that channels 0 and 3 are disabled, and channels 1 are 2 and enabled. Care should be taken not to exceed the maximum bus capacity.

8. Application and Implementation

Applications of the NCA9546 will contain an I²C (or SMBus) master device and up to four I²C slave devices. The downstream channels are ideally used to resolve I²C slave address conflicts. For example, if four identical digital temperature sensors are needed in the application, one sensor can be connected at each channel: 0, 1, 2, and 3. When the temperature at a specific location needs to be read, the appropriate channel can be enabled and all other channels switched off, the data can be retrieved, and the I²C master can move on and read the next channel.

In an application where the I²C bus will contain many additional slave devices that do not result in I²C slave address conflicts, these slave devices can be connected to any desired channel to distribute the total bus capacitance across multiple channels. If multiple switches will be enabled simultaneously, additional design requirements must be considered (See Design Requirements and Detailed Design Procedure).

8.1. Typical Application

A typical application of the NCA9546 will contain anywhere from 1 to 5 separate data pull-up voltages, V_{DPUX} , one for the master device (V_{DPUM}) and one for each of the selectable slave channels ($V_{DPU0} - V_{DPU3}$). In the event where the master device and all slave devices operate at the same voltage, then the pass voltage, $V_{pass} = V_{DPUX}$. Once the maximum Vpass is known, Vcc can be selected easily using Figure 8.1 In an application where voltage translation is necessary, additional design requirements must be considered (See Design Requirements).

Figure 8.1 shows an application in which the NCA9546 can be used.

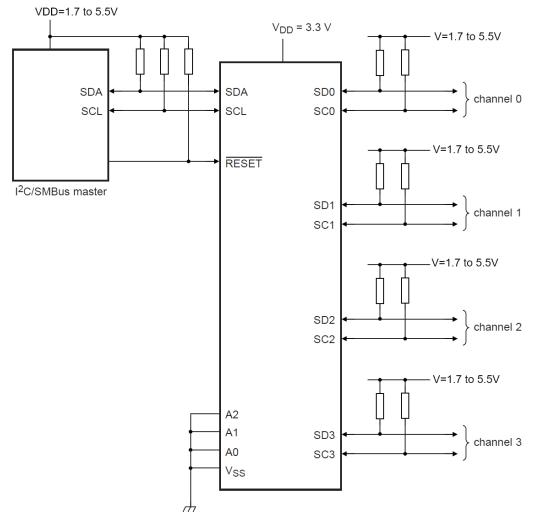


Figure 8.1 Typical Application Schematic

8.2. Design Requirements

The A0, A1 and A2 terminals are hardware selectable to control the slave address of the NCA9546. These terminals may be tied directly to GND or VCC in the application.

If multiple slave channels will be activated simultaneously in the application, then the total I_{OL} from SCL/SDA to GND on the master side will be the sum of the currents through all pull-up resistors, R_P.

The pass-gate transistors of the NCA9546 are constructed such that the VCC voltage can be used to limit the maximum voltage that is passed from one I²C bus to another.

Figure 8.2 shows the voltage characteristics of the pass-gate transistors (note that the graph was generated using data specified in the Electrical Characteristics section of this data sheet). In order for the NCA9546 to act as a voltage translator, the V_{pass} voltage must be equal to or lower than the lowest bus voltage. For example, if the main bus is running at 5 V and the downstream buses are 3.3 V and 2.7 V, V_{pass} must be equal to or below 2.7 V to effectively clamp the downstream bus voltages. As shown in Figure 8.2, Vpass(max) is 2.7 V when the NCA9546A supply voltage is 4 V or lower, so the NCA9546A supply voltage could be set to 3.3 V. Pull-up resistors then can be used to bring the bus voltages to their appropriate levels (see Figure 8.1).

8.3. Detailed Design Procedure

Once all the slaves are assigned to the appropriate slave channels and bus voltages are identified, the pull-up resistors, R_p, for each of the buses need to be selected appropriately. The minimum pull-up resistance is a function of V_{DPUX}, V_{OL, (max)}, and _{IOL}:

$$R_{p(min)} = \frac{V_{DPUV} - V_{OL(max)}}{I_{OL}}$$
 (1)

The maximum pull-up resistance is a function of the maximum rise time, tr (300 ns for fast-mode operation, f_{SCL} = 400 kHz) and bus capacitance, C_b :

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \tag{2}$$

The maximum bus capacitance for an I²C bus must not exceed 400 pF for fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the NCA9546, C_{io(OFF)}, the capacitance of wires/connections/traces, and the capacitance of each individual slave on a given channel. If multiple channels will be activated simultaneously, each of the slaves on all channels will contribute to total bus capacitance.

8.4. NCA9546 Application Curves

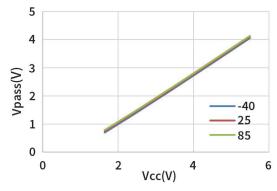
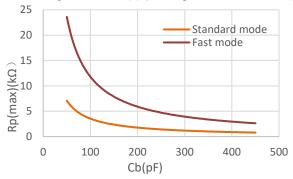
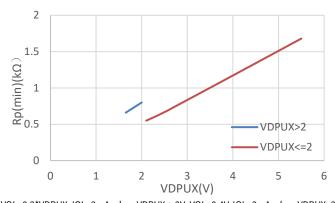


Figure 8.2 Pass-Gate Voltage (V_{pass}) vs Supply Voltage (V_{CC}) at Three Temperature Points



Standard mode (fscl=100kHz, tr=1us); Fast mode: (fscl=400kHz,tr=300ns) Figure 8.3 Maximum Pull-Up resistance ($R_D(max)$) vs Bus Capacitance (C_D)



VOL=0.2*VDPUX, IOL=2mA when VDPUX<=2V; VOL=0.4V, IOL=3mA when VDPUX>2V Figure 8.4 Minimum Pull-Up resistance ($R_{p(min)}$) vs Pull-up reference voltage (V_{DPUX})

9. Layout

9.1. Layout Guidelines

For PCB layout of the NCA9546, common PCB layout practices should be followed but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I²C signal speeds. It is common to have a dedicated ground plane on an inner layer of the board and terminals that are connected to ground should have a low-impedance path to the ground plane in the form of wide polygon pours and multiple vias. By-pass and de-coupling capacitors are commonly used to control the voltage on the VCC terminal, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple.

In an application where voltage translation is not required, all VDPUX voltages and VCC could be at the same potential and a single copper plane could connect all of pull-up resistors to the appropriate reference voltage. In an application where voltage translation is required, V_{DPUM}, V_{DPUO}, V_{DPUO}, V_{DPUO}, and V_{DPUO} may all be on the same layer of the board with split planes to isolate different voltage potentials.

To reduce the total I²C bus capacitance added by PCB parasitics, data lines (SCn, SDn and INTn) should be a short as possible and the widths of the traces should also be minimized (e.g. 5-10 mils depending on copper weight).

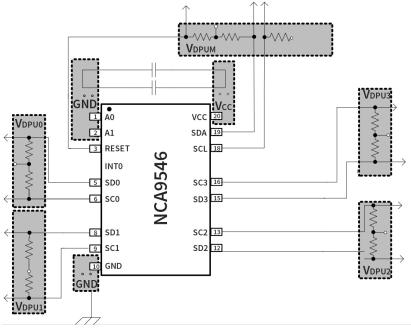
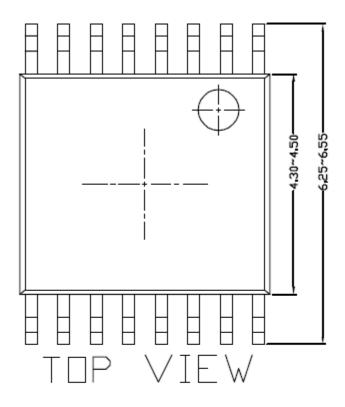
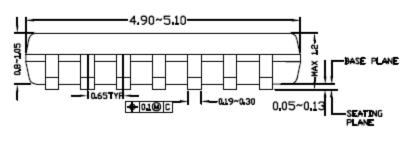


Figure 9.1 Typical Application PCB

10. Package Information





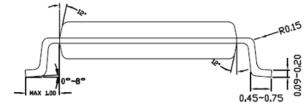
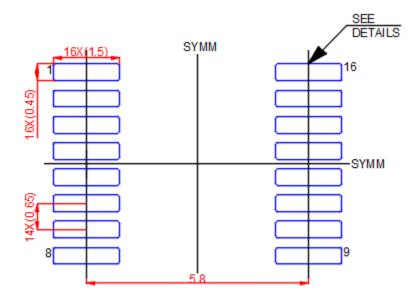
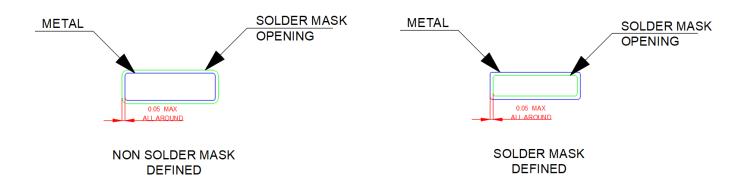


Figure 10.1 Package outline for TSSOP16



LAND PATTERN EXAMPLE(mm)



SOLDER MASK DETAILS

Figure 10.2 TSSOP16 Package Board Layout Example

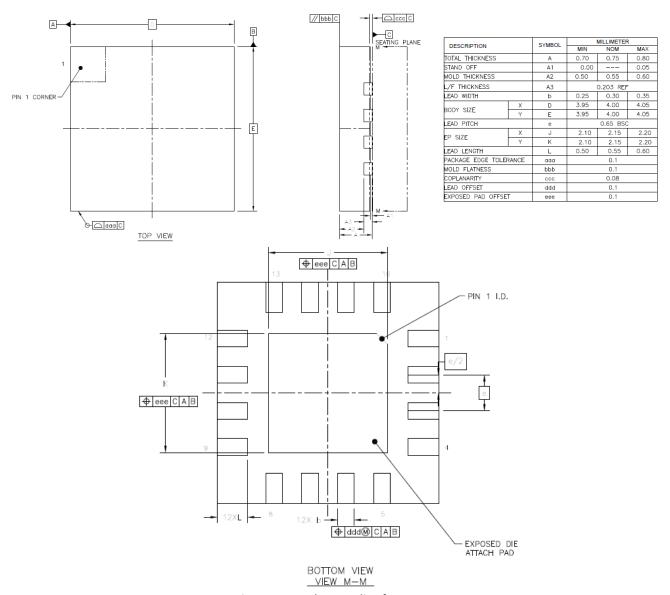
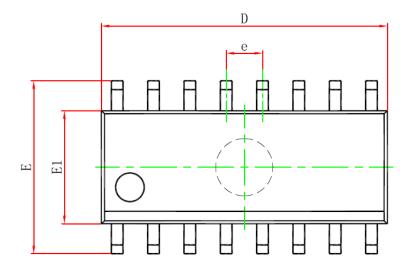
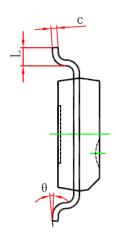
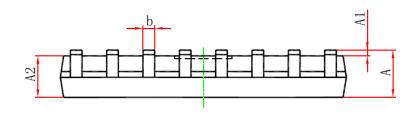


Figure 10.3 Package outline for QFN16







Symbol	Dimensions In	Millimeters	Dimensions In Inches		
Symbor	Min	Max	Min	Max	
A		1.750		0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.400	1.500	0.055	0.059	
ъ	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.007	0.010	
D	9.800	10.200	0.386	0.402	
e	1.270 ((BSC)	0.050 (BSC)		
Е	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0 °	8°	

Figure 10.4 Package outline for SOP16

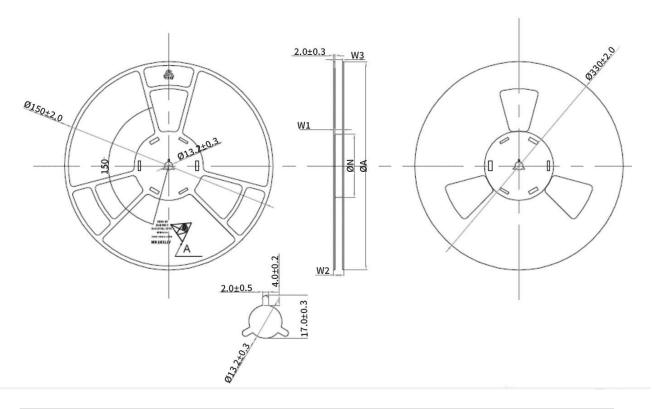
11. Order information

Part Number	Temperature	MSL	Package Type	Package Drawing	Package Qty
NCA9546-DTSPR	-40 to 105°C	2	TSSOP16	TSSOP16	3000
NCA9546-DQNPR	-40 to 105°C	3	QFN16	QFN16	2500
NCA9546-DSPNR	-40 to 105°C	3	SOP16	SOP16	4000
			(150mil)		

12. Documentation Support

Part Number	Product Folder	Datasheet	Technical Documents	Isolator selection guide
NCA9546	Click here	Click here	Click here	Click here

13. Tape and Reel Information



PRODUCT SPECIFICATIONS					
TAPE WIDTH	ØA	ØN	W1 (+2/0)	W2 (Max)	W3 _(Max)
12MM	330±2.0	100±1.0	12.4	18.4 🛕	11.9/15.4
16MM	330±2.0	100±1.0	16.4	22.4 <u>B</u>	15.9/19.4
24MM	330±2.0	100±1.0	24.4	30.4 🛕	23.9~27.4

Figure 13.1 Reel Information

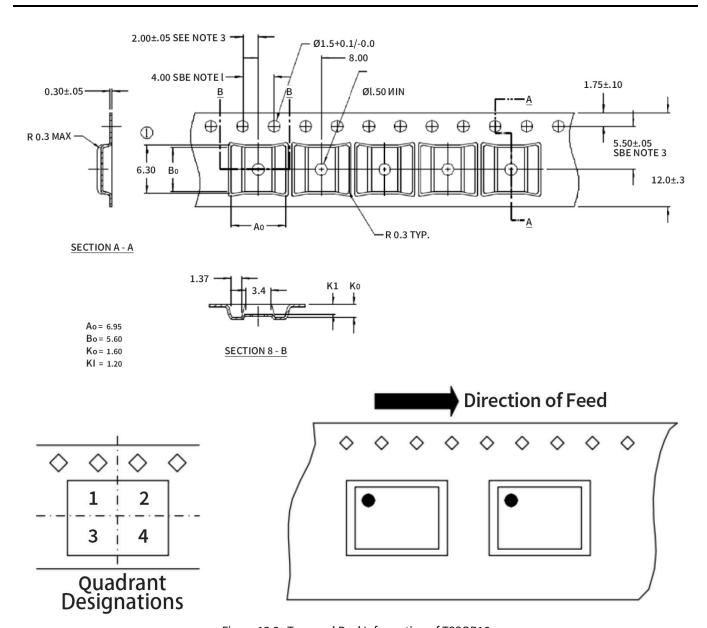


Figure 13.2 Tape and Reel Information of TSSOP16

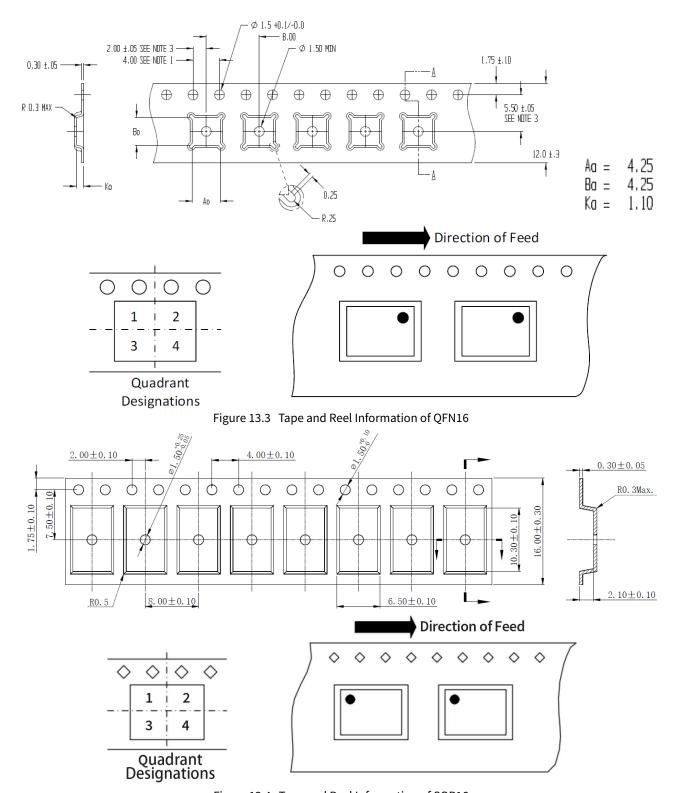


Figure 13.4 Tape and Reel Information of SOP16

14. Revision History

Revision	Description	Date
1.0	Initial version	2021/4/2
1.1	Supply voltage range changed	2021/11/11
1.2	Changed Control Register Definition. Update TSSOP16 Package Board Layout	2022/3/24
	Example. Change Storage Temperature.	
1.3	Corrected timing information and added QFN16 and SOP16 package	2024/4/11
	information	

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